

DF2005S THRU DF210S**List**

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing and tube packing.....	6
Suggested thermal profiles for soldering processes.....	6
High reliability test capabilities.....	7

DF2005S THRU DF210S

2.0A Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifiers-50-1000V

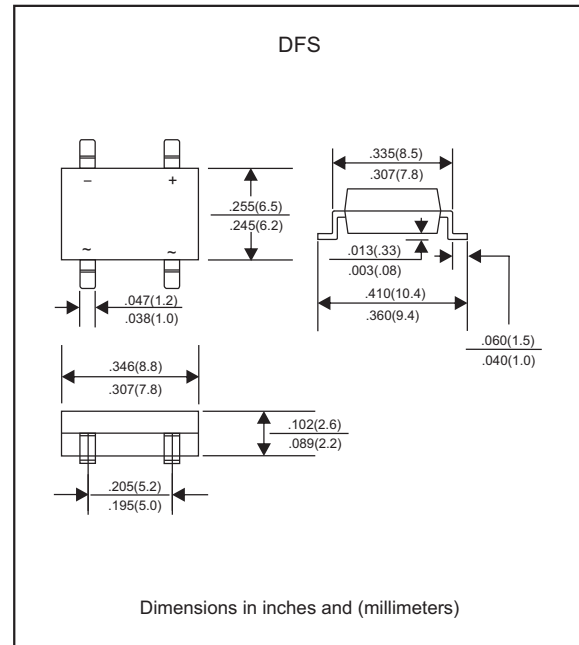
Features

- Surge overload ratings to 60 amperes peak.
- Surface mount type for automated replacement.
- Ideal for printed board.
- Low forward drop down voltage.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- UL recognized file # E321971
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex. DF2005S-H.

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DFS
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 0.34 gram

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			60	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			10	uA
	$V_R = V_{RRM} \quad T_J = 125^{\circ}\text{C}$				500	
I^2t Rating for Fusing	$t < 8.3\text{ms}$	I^2t			15.0	A^2s
Typical Junction Capacitance Per Element	Measured at 1.0MHz and applied reverse voltage of 4.0V DC	C_J		25		pF
Typical thermal resistance	Junction to ambient mounted on P.C.B with 0.5*0.5"(13*13mm) copper pads.	$R_{\theta JA}$		40		$^{\circ}\text{C/W}$
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^{\circ}\text{C})$
DF2005S	50	35	50	1.10	-55 to +150
DF201S	100	70	100		
DF202S	200	140	200		
DF204S	400	280	400		
DF206S	600	420	600		
DF208S	800	560	800		
DF210S	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=2.0\text{A}$

Rating and characteristic curves (DF2005S THRU DF210S)

FIG.1-DERATING CURVE FOR
OUTPUT RECTIFIED CURRENT

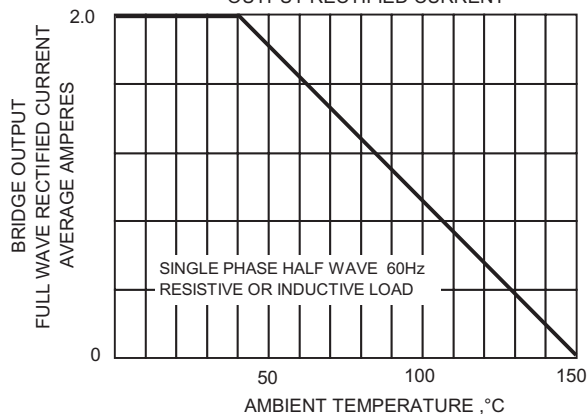


FIG.2-MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT

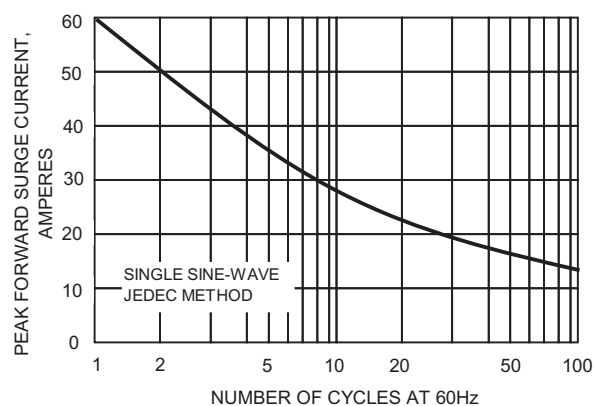


FIG.3-TYPICAL JUNCTION CAPACITANCE

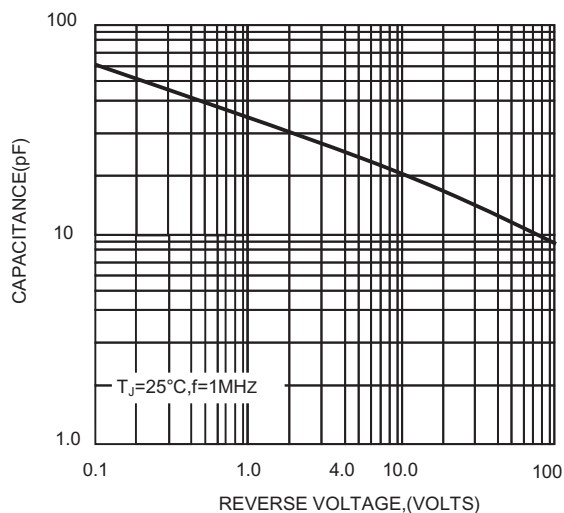


FIG.4-TYPICAL FORWARD CHARACTERISTICS

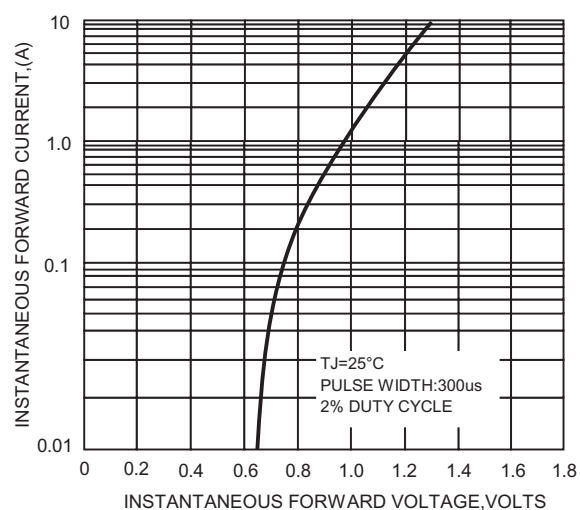
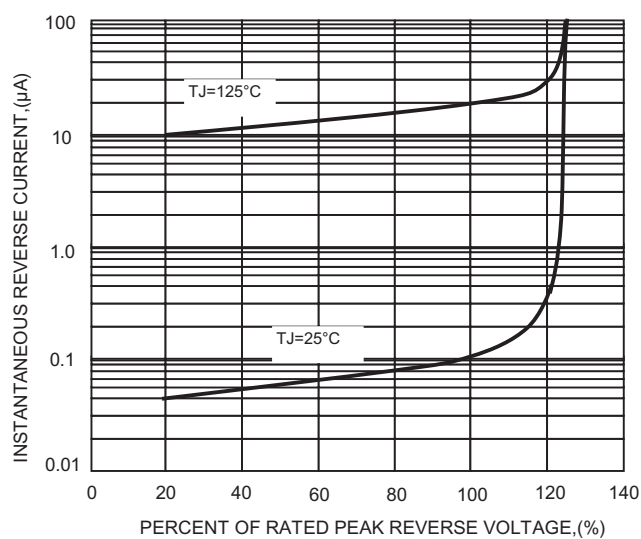
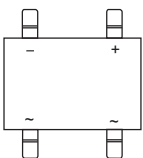
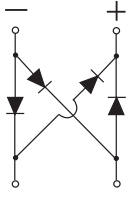


FIG.5-TYPICAL REVERSE CHARACTERISTICS



DF2005S THRU DF210S

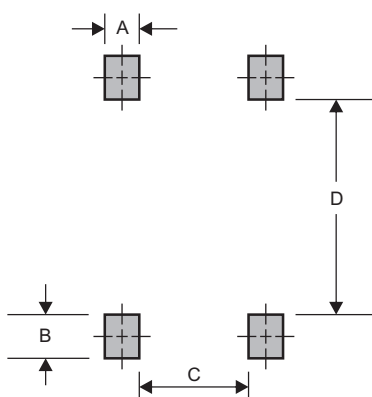
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code
DF2005S	DF2005S
DF201S	DF201S
DF202S	DF202S
DF204S	DF204S
DF206S	DF206S
DF208S	DF208S
DF210S	DF210S

Suggested solder pad layout

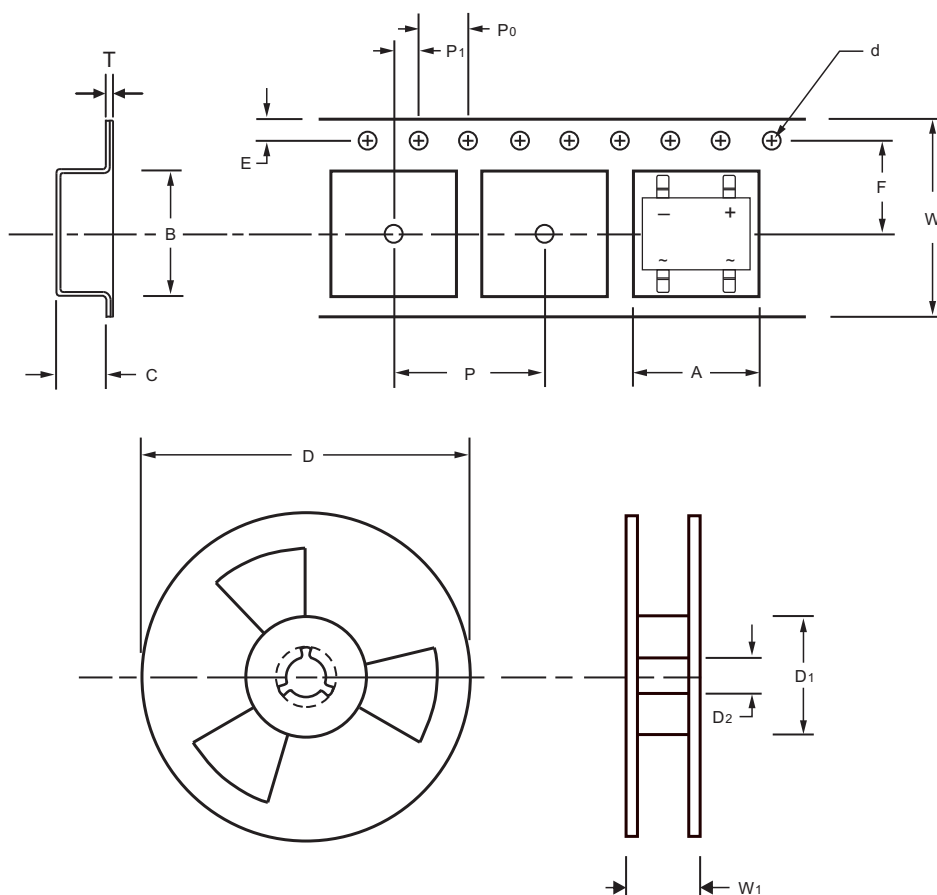


Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
DFS	0.059 (1.50)	0.047 (1.20)	0.157 (4.00)	0.291 (7.40)

DF2005S THRU DF210S

Packing information



unit:mm

Item	Symbol	Tolerance	DFS
Carrier width	A	0.1	8.64
Carrier length	B	0.1	10.41
Carrier depth	C	0.1	3.50
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D1	min	-
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	12.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	16.00
Reel width	W1	1.0	22.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing and tube packing

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DFS	50	423*12.0*4.8	452*164*130	10,000	5.4

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



DF2005S THRU DF210S

High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031